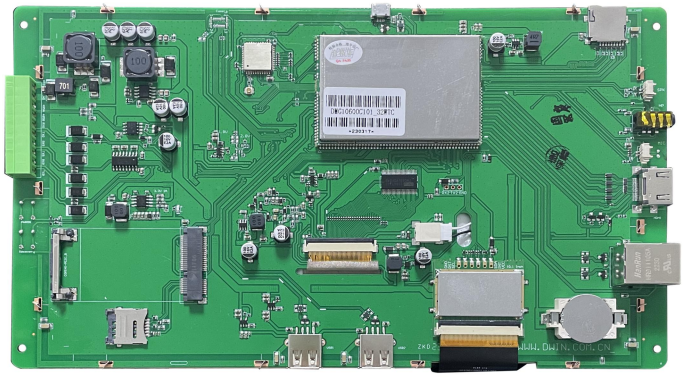
DMG10600C101_32WTC



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System Hardware

Properties	Parameters
Motherboard level	Commercial-grade
CPU	RK3566, Quad-core ARM Cortex-A55, 1.8GHz Processor
OS	Android 11
Storage	8Gbytes eMMC
RAM	2Gbytes LPDDR4

Display Parameters

Properties	Parameters	Description
Size	10.1 inch	-
LCD Type	IPS, TFT LCD	-
Viewing Angle	85° /85° /85° /85°	Wide viewing angle, high contrast, and good color reproduction
Active Area (AA)	222.72mm (W)*125.28mm (H)	-
Resolution	1024x600	-
Backlight Service Life	>20000 Hrs	Backlight service life refers to the period the LED backlight operates under test conditions until brightness decreases to 50% of the initial level
Brightness	200nit	100-level brightness adjustment (Flickering may occur at 1%-30% of max brightness; not recommended for use in this range)
Note: Use dynamic screen saver to prevent afterimages from prolonged fixed page display.		

Touch Parameter

Properties	Parameters
Touch Type	Capacitive touch panel
Structure	G+G structure with tempered glass surface

Power Supply

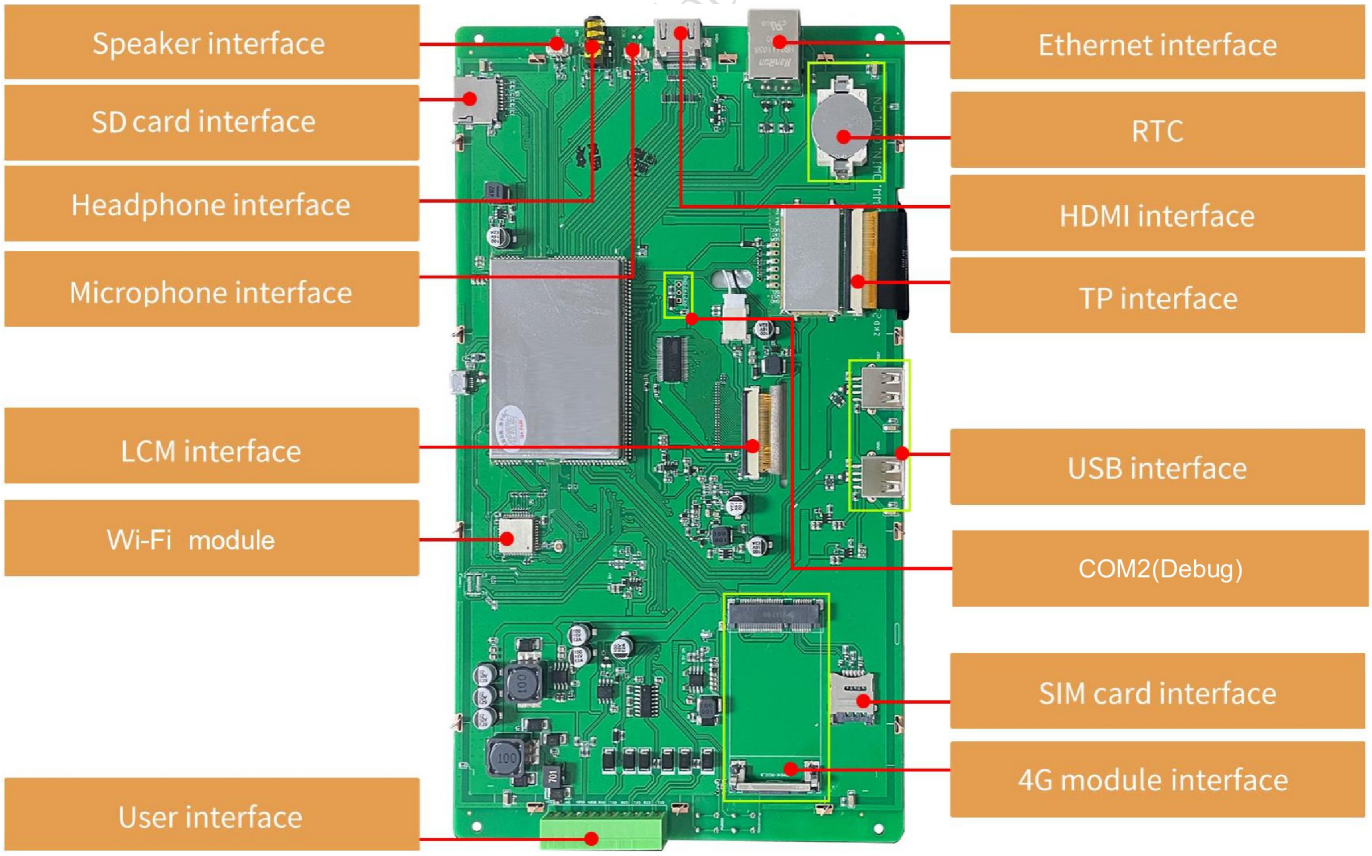
Properties	Min	Typ	Max	Unit
Power Voltage	9.0	12.0	36.0	V
Recommended power supply:12V 1A DC.				

Environment & Reliability Test

Properties	Conditions	Min	Typ	Max	Unit
Working Temperature	60%RH at 12V voltage	-20	25	65	℃
Storage Temperature	-	-30	25	80	℃
Working Humidity	25℃	10%	60%	90%	RH
Conformal Coating	Y				
ESD	Air: ±8KV; Contact: ±4KV				
EFT	Group pulse interference±2KV				
CE Certification	Y				
Additional cooling required for operation above 65℃.					

Peripherals and Interfaces

Properties	Description
User Interface	10Pin_3.81mm Horizontal socket
COM	RS232*2(COM5 & COM9), RS485*1(COM8), TTL*1(COM0),TTL*1(COM2, debug)
Wi-Fi	IEE 802.11b/g/n, 2.4GHz, Wi-Fi 4
Bluetooth Version	BT4.2
Ethernet	10/100Mbps
USB	USB 2.0*2(HOST), Micro USB*1(OTG)
SD Card	Max 64G
RTC	Accuracy: ±20ppm @25℃
Speaker	2Pin_1.25mm interface*1
Microphone	2Pin_1.25mm interface*1
Headphone	3.5mm spacing interface
Camera	USB, not supported by MIPI
4G module	Factory not configured, customizable to add
HDMI interface	HDMI*1



Development Platform

Development	
Android	Java, Kotlin, C++

Packing Capacity & Dimension

Dimension				
Dimension	257.81(W)*148.08(H)*23.20(T)mm			
Net Weight	620g			
Packing Capacity				
Model	**Size**	**Layer**	**Quantity/Layer**	**Quantity(Pcs)**
Carton1:	220mm(L)*160mm(W)*47mm (H)	-	-	-
Carton2:	250mm(L)*200mm(W)*80mm (H)	-	-	-
Carton3:	320mm(L)*270mm(W)*80mm (H)	2	1	2
Carton4:	450mm(L)*350mm(W)*300mm(H)	1	10	10
Carton5:	600mm(L)*450mm(W)*300mm(H)	1	16	16

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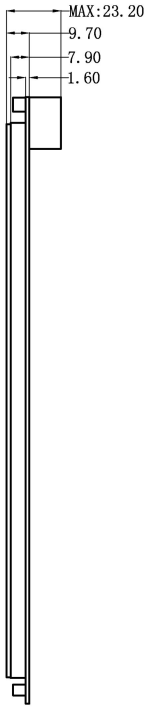
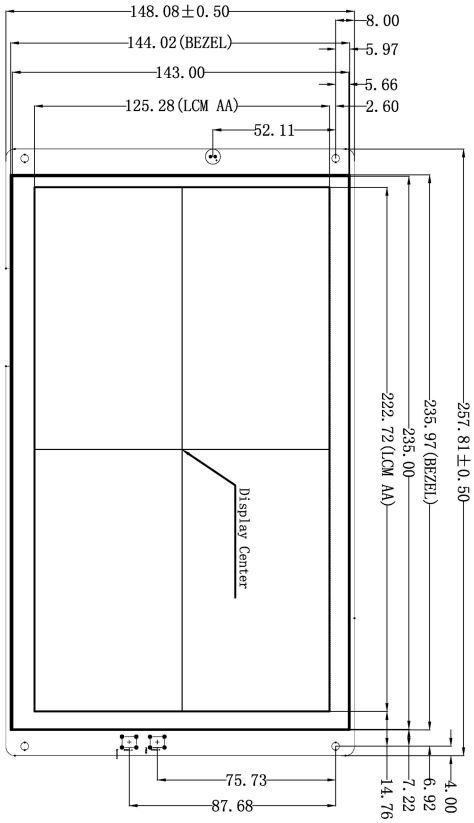
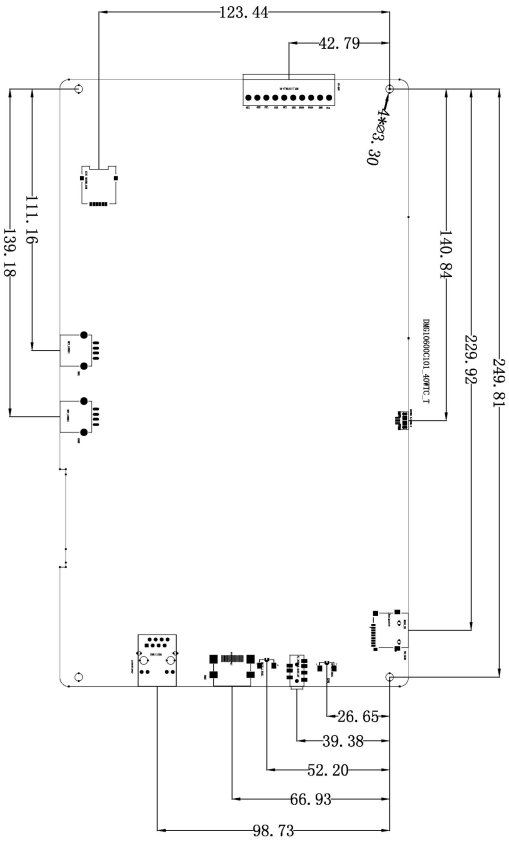
Definition	Pin#	IO	Description
VCC	1	P	Power Input
GND	2	P	GND
485A	3	A	RS485+
485B	4	B	RS485-
RX0	5	I	UART 0 Input
TX0	6	O	UART 0 Output
RX5	7	I	UART 5 Input
TX5	8	O	UART 5 Output
RX9	9	I	UART 9 Input
TX9	10	O	UART 9 Output







Location hole is used as position reference.

Unmarked Tolerance is +/-0.3mm

Active area is marked in Dash lines

				Model	DMG10600C101_32WTC
				Drawing	A 4
				Scale	1:1
				Unit	MM
				Drawn	G.Y
				Review	
				Approval	
				Date	2023.01.06
				Date	
				Date	
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Revision Records

Ver	Revise Date	Content	Editor
00	2023-01-11	First edition	YML
01	2023-05-15	Remove the 4G module and update the physical image	YML
02	2023-11-03	ESD grade updated	YML
03	2024-12-31	Modify the voltage value range, add development	Chen
04	2025-03-12	Add the description of Bluetooth	Chen
05	2025-04-02	Update the range of temperature	Chen
06	2025-06-17	Update the description of Wi-Fi module	Chen

Please contact us if you have any questions about the use of this document or our products, or if you would like to know the latest information about our products:

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Thank you all for continuous support of DWIN, and your approval is the driving force of our progress!

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